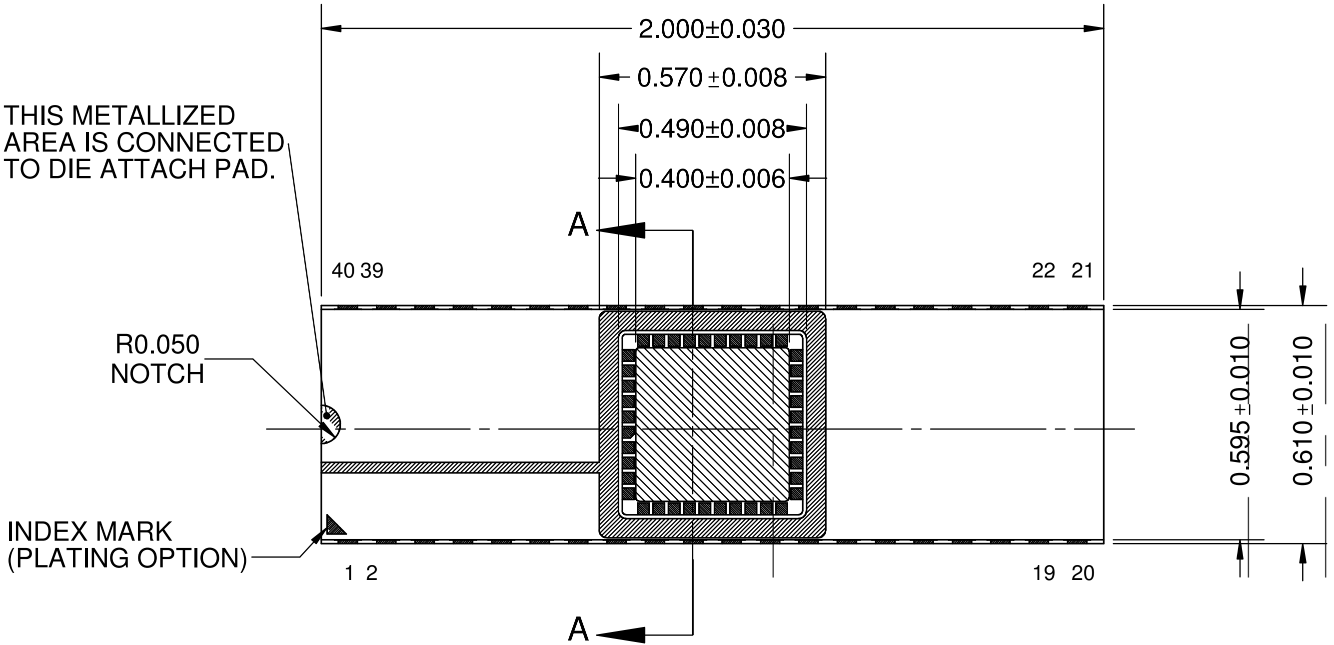
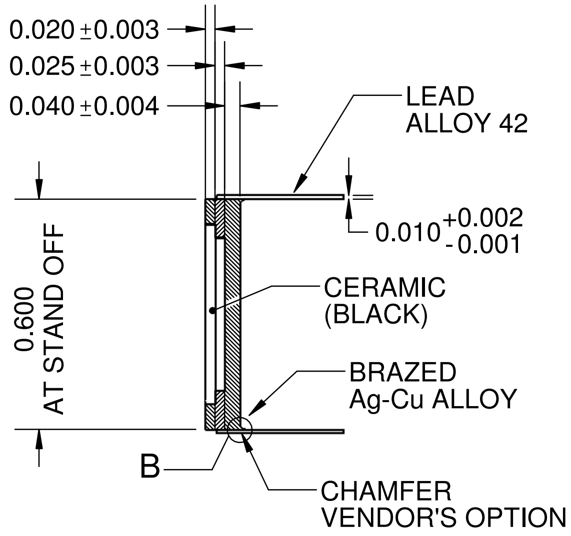
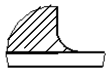
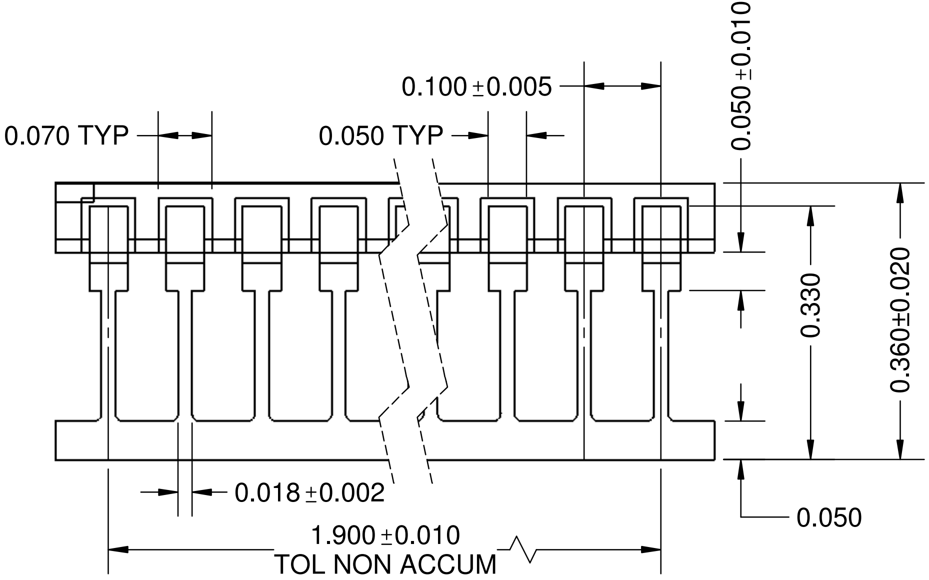






DETAIL B
SCALE 8 : 1

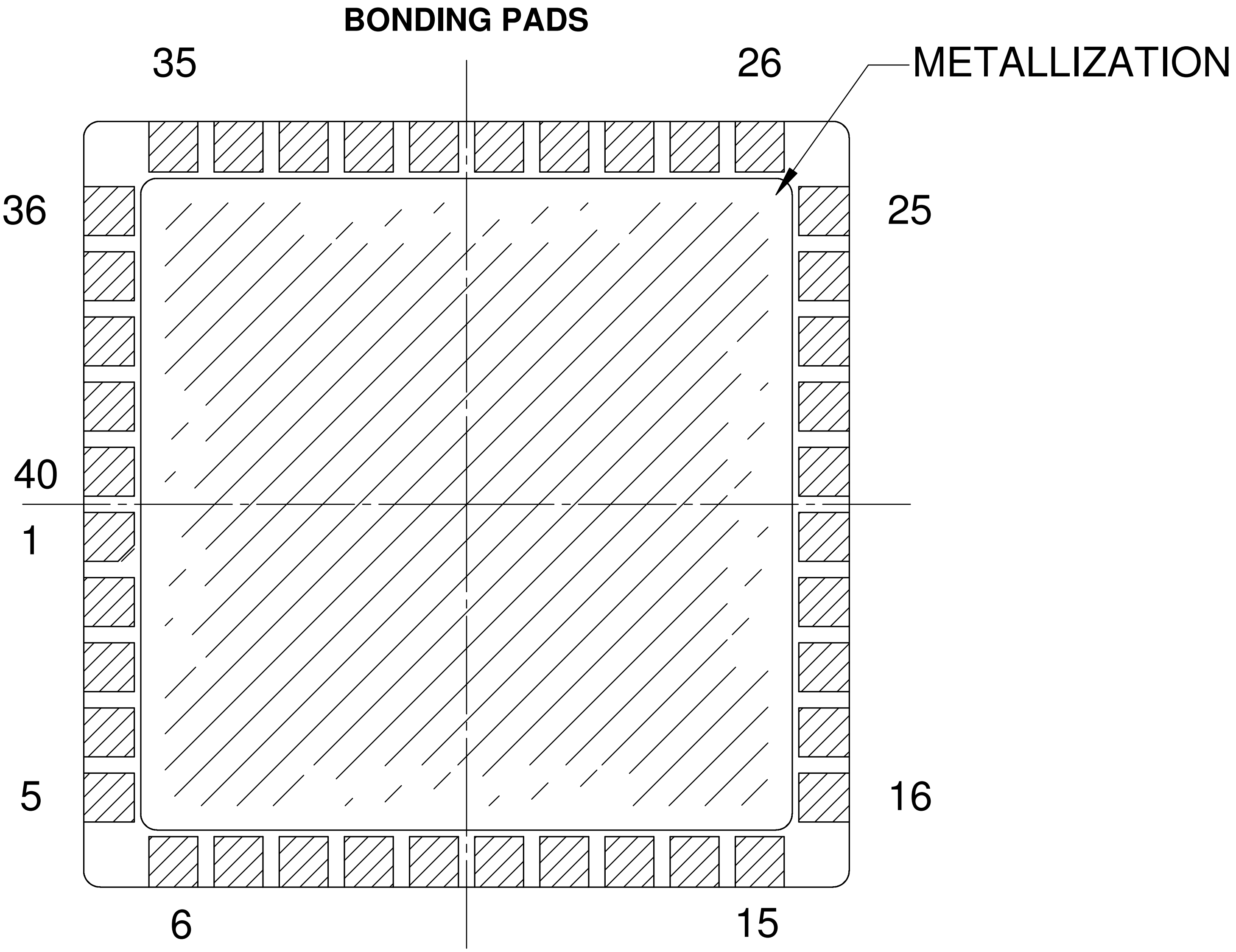


NOTES:
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
2. SEAL AREA TO BE METALLIZED.
3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.35 OHM MAX.
6. TOLERANCE ±0.005-INCH UNLESS OTHERWISE SPECIFIED.
7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE

PART NUMBER	DIE PAD	DWG
CERDIP40F6-N400	GOLD	170295

APPROVALS		DATE	TopLine®			
DRAWN	T.Au	1/4/2017				
ENG	M. Hart	1/4/2017	TITLE	CERDIP40F6-N400 DIE PAD 400 MIL (10.1mm) SQ		
MFG						
QA			SCALE 2:1	SIZE A	DRAWING NO. 170295	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 3	

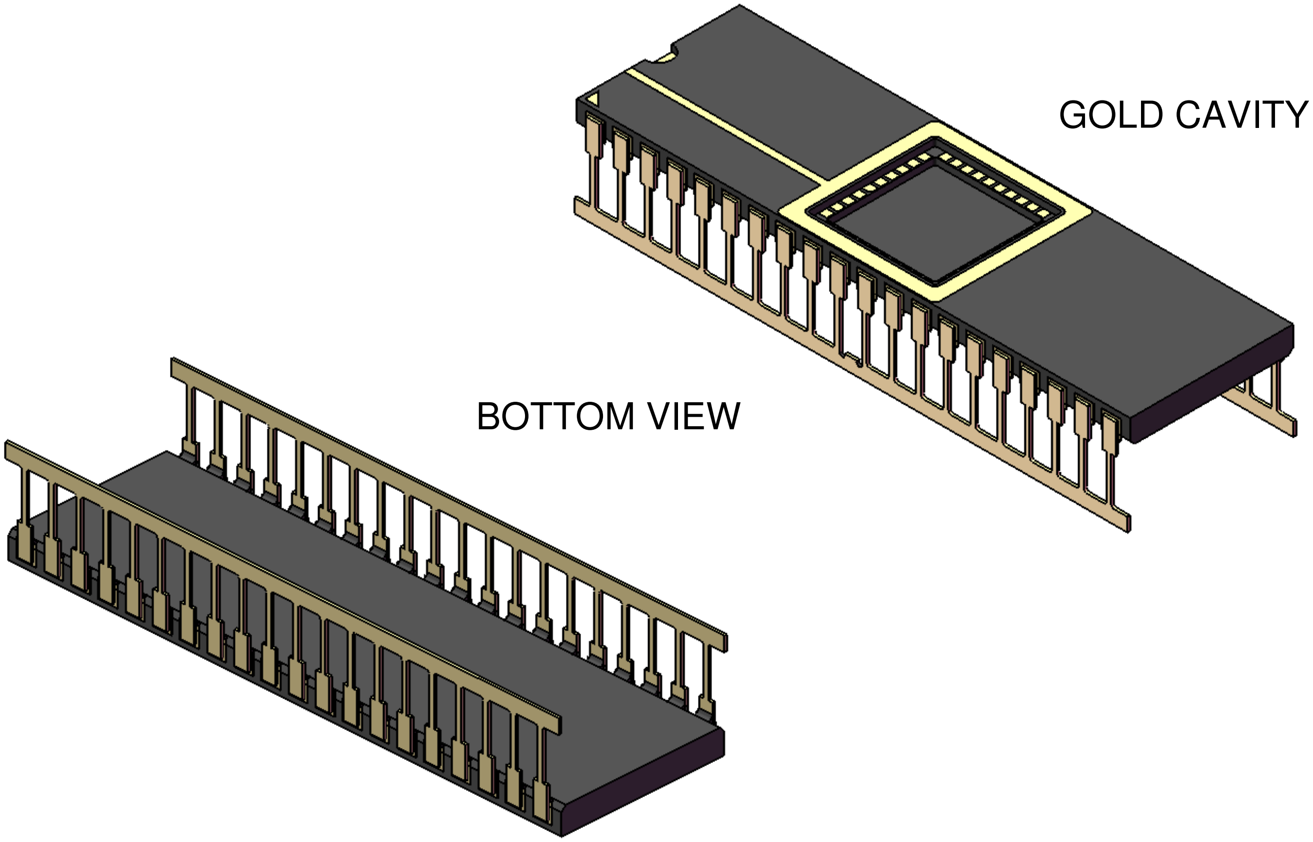


PART NUMBER TABLE		
PART NUMBER	**DIE PAD**	**DWG**
CERDIP40F6-N400	GOLD	170295

TopLine®

TITLE CERDIP40F6-N400 DIE PAD 400 MIL (10.1mm) SQ			
SCALE 10:1	SIZE A	DRAWING NO. 170295	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 3	

MODELS



PART NUMBER TABLE		
PART NUMBER	**DIE PAD**	**DWG**
CERDIP40F6-N400	GOLD	170295

TopLine®

TITLE	CERDIP40F6-N400 DIE PAD 400 MIL (10.1mm) SQ		
SCALE 2.5:1	SIZE A	DRAWING NO. 170295	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 3	